

What is claimed is:

- 1 1. An LED lamp, comprising:
2 a package; and
3 a plurality of light emitting elements that are
4 electrically connected to a plurality of electrode plates
5 provided in the package and that are sealed with transparent
6 material;
7 wherein a red light emitting element of the plurality of
8 light emitting elements is wire bonded along the longitudinal
9 direction of the package, a green light emitting element and
10 a blue light emitting element are flip-chip bonded with its
11 electrode faced down, and the electrodes are extended to a
12 surface opposite to the light emission surface of the LED lamp
13 while being embedded in the package.
- 1 2. The LED lamp according to claim 1, wherein:
2 the red light emitting element is a plurality of red light
3 emitting elements, and every two of the plurality of red light
4 emitting elements are connected in series.
- 1 3. The LED lamp according to claim 1, wherein:
2 the package is of ceramics material.
- 1 4. An LED lamp, comprising:
2 a circuit board with a wiring pattern formed thereon; and
3 a package that houses a light emitting element, the
4 package being mounted on the circuit board;
5 wherein the package is provided with a terminal that is

6 electrically connected to the wiring pattern by using solder,
7 and part of the terminal and/or the wiring pattern is provided
8 with a cutting region that allows the retention of solder to
9 be flown thereinto.

1 5. The LED lamp according to claim 4, wherein:
2 the cutting region is formed by cutting off part of a
3 mounting surface of the package together with part of the
4 terminal.

1 6. The LED lamp according to claim 4, wherein:
2 the terminal is part of a conductive film pattern.

1 7. The LED lamp according to claim 4, wherein:
2 the package is formed by staking a plurality of ceramics
3 plates and then baking the plates.

1 8. The LED lamp according to claim 4, wherein:
2 the package is formed by cutting an assembly that a
3 plurality of packages are integrally formed, and the cutting
4 region is formed at a cutting face in cutting the assembly.

1 9. A method of making an LED lamp, comprising the steps
2 of:

3 preparing a first thin plate with an opening, a second
4 thin plate with a first wiring pattern formed thereon, and a
5 third thin plate with a second wiring pattern formed thereon;
6 stacking the first thin plate, the second thin plate and
7 the third thin plate in this order;

8 baking the stacked first thin plate, the second thin plate
9 and the third thin plate to provide an assembly integrating the
10 first to third thin plates;
11 mounting an LED in the opening and electrically
12 connecting the first wiring pattern to the LED; and
13 cutting the assembly in a predetermined pattern.

1 10. The method according to claim 9, wherein:
2 the second wiring pattern is provided with a recess in
3 a predetermined shape formed at its part, the cutting step is
4 conducted by cutting the assembly along the recess to have a
5 cutting region at part of the second wiring pattern of LED lamp.